HCAL HTR Pre-Production board specifications

Last update: Jan 30, 2002 - Last Changes are in blue

The main use of this board is from May 2003 in Cern for Test beam and Slice tests.

In Cern are needed 11 boards + spares. In USA (UMD, BU, FNAL, Princeton) we need more boards to keep development. Thus we should produce about 25 boards.

1. Changes from prototype board

[compare with HCAL HTR Prototype board specifications and design guidelines available on: http://www.physics.umd.edu/hep/tullio/proto/HTRproto board specs.pdf]

- add a TTC daughter card.
- add 6 SLBs on front-panel.
- The Front-Panel switches will be moved back and routed to the xilinx. The same for the sel line of the clock mux (Xtal or Clean clk).
- JTAG an all devices that support it, possibly also for the programming of the gate arrays with the cable would be better with JTAG. Put jumper scheme to by-pass any device in the chain.
- on the VME FPGA there is an input clock from the VME back-plane. Replace it with a crystal oscillator.
- The reason is that this chip does not need synchronization with the rest of the board.
- Fiber input using the 8-channel passive Molex MTP Adapter on the front-panel and Stratos dual LC on board
- add stiffeners and possibly metal edges of the board.
- Connectors for Logic Analyzer in Local Data, Local Address, Local other
- Every data connector of the SLB has half of its inputs from each of the 2 xilinx FPGAs.
- put ground "island" under all high-speed devices and clock drivers.
- The HTR prototype hangs up the bus when altera is not configured, find out why.
- In the unused portion of the board, put plenty of VCC and GND pads for reworking.

2. Board Input/Output

FE-Data Input

This data come on eight 100-meter optical fibers, 850nm, multimode 62.5/125 from the Cern GOL serializer to the MTP adapters. From there, there is an 8-way MTP-to-LC fanout going to the SFF dual LC receivers PN M2R-25-9-TL from StratosLightWave. The data-stream is on 1.6 Gb/s differential lines (DINRXP-DINRXN). Data are deserialized and 8B/10B decoded by eight TLK2501 parts (2.5V parts).

Timing Inputs

Timing signal are received via one RJ45 on a Cat 6E (or Cat7) cable. The TTC stream is a 160 MHz signal, RX_BC0 is a 40 MHz signal, RX_CLK is 40 MHz (jitter \sim 80ps pk-pk) and Clean_CLK is 80 MHz (jitter \sim 50ps pk-pk). On clock signals the jitter should be minimized. The input connector is AMP 558342-1.

| Pin | Signal | Pin | Signal |
|-----|---------------------|-----|--------------|
| 1 | TTC-serial_P | 2 | TTC-serial_N |
| 3 | Rx_CLK_P (40 MHz) | 4 | Rx_BC0_P |
| 5 | Rx_BC0_N | 6 | Rx_CLK_N |
| 7 | CleanCLK_P (80 MHz) | 8 | CleanCLK_N |

Table 1: Pin-out definitions on the RJ45 connector (pinning standard RG568B). All signals are 3.3V differential PECL.

The timing scheme is on a separate pdf document. Add buffers and terminations as needed.

RX_CLK and RX_BC0 have same length path to all SLBs (± 1 inch = 100 ps skew); the RX_BC0 pair go to the Xilinx chips to two adjacent pads: IO_LXXP_# and IO_LXXN_#, with XX a unique pair in the bank and # indicates the bank number (0 through 7).

The signals Brodcst[7:2], BrdcstStr, BcntRes, EvCntRes, L1A and Clk40Des1 come from the TTC mezzanine and go to the 2 xilinx chips and to the 6 SLBs. TTC_Reset_b and TTCready are routed to one xilinx chip only.

Add a pair Test_CLK+/- from two test points to two diff. GCLK input of each xilinx.

Connect TTCready and TTCreset b to a xilinx.

L1-Trigger outputs

Those are 24 x 9 lines from each Xilinx FPGA. They will be source terminated inside the FPGA. This requires that the xilinx N reference pin (VRN) be pulled up to VCCO by a 50 Ohm reference resistor, and the P reference pin (VRP) must be pulled down to ground by another 50 Ohm reference resistor (1/10 watt or more). The top xilinx send the following outputs:

TP1[8:0], TP2[8:0], ..., TP24[8:0]

To these inputs of each SLB: Sync1_[8:0], Sync2_[8:0], Sync5_[8:0] and Sync6_[8:0]

The bottom xilinx to the connector 2 send the following outputs:

TP25[8:0], TP26[8:0], ..., TP48[8:0]

To these inputs of each SLB: Sync3_[8:0], Sync4_[8:0], Sync7_[8:0] and Sync8_[8:0]

L2-DAQ-Data Output

The only change from the HTR prototype is that the output connector is RJ-45, 5 pairs.

The connector is made by Stewart, P/N SS-701010-NF, available from Arrow.

Driver-to-connector assignment is as on the top-right side of:

http://ohm.bu.edu/~hazen/my_d0/TxRx/ltb_2_5/LTB_sch.pdf

3. Main HTR FPGA

| Candidates | BRAM | I/O pins | Bitstream Length | \$ (Avnet, >25pcs, Sep 02) | \$ (Insight, ~100pcs Oct 02) |
|-----------------------|------|----------|------------------|-------------------------------|------------------------------|
| XC2V2000- 4BF957C | 56 | 624 | 7,492,000 bits | 590 | 472 |
| XC2V3000- 4BF957C | 96 | 720 | 10,494,368 bits | 930 | 743 |
| XC2V4000- 4BF957C | 120 | 912 | 15,659,936 bits | 1552 | |
| XC2V2000- 4FF896C | 56 | 624 | 7,492,000 bits | 590 | |
| XC2V3000- 4FF1152C | 96 | 720 | 10,494,368 bits | 930 | |
| XC2V3000- 4BG728C | 96 | 516 | 10,494,368 bits | 852 | |

Option 1) is our baseline. In case we need more resources options 1) and 2) are pin-out (footprint) compatible [Virtex-II handbook, page 42, Oct 2001].

Connect possibly ~4-wire switch, ~10 test points, ~2 LEDs to some unused pins.

Power connections: $V_{CCO} = 2.5V$; $V_{CCAUX} = 3.3V$.

Pin VRN must be pulled up to Vcco=2.5V by its 60 Ohm reference resistor. Pin VRP must be pulled down to ground by its 60 Ohm reference resistor.

4. VME FPGA: requirements and candidates

This FPGA will implement:

- ➤ The interface to the VME bus
- ➤ The configuration of the Main FPGAs and of the FLASH devices
- > The master of the *Local Bus*

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Requirement:
- 5V-tolerant
- System-gates: > 1000 Altera LCs
- No BGA
- No old parts
VME FPGA candidate devices:
 Altera Acex
              EP1K30QC208-3 208-Pin PQFP $17
 Altera Acex
             EP1K50QC208-3 208-Pin PQFP $22 SELECT THIS ONE!
 Xilinx Spartan
======VME FPGA pin candidates ======
\CONFIG CS1
\CONFIG CS2
\CONFIG PROG
\CONFIG WRITE
\FLASH_1_CE
\FLASH 1 OE
\FLASH 1 WE
\FLASH 2 CE
\FLASH 2 OE
\FLASH 2 WE
\GA0
\GA1
\GA2
\backslash GA3
\GA4
\VME AS
\VME_DATA_OEB (I think this could be just pull-down + test point)
\VME_DS0
\VME DS1
VME DTACK
\VME_LWORD
VME RESET
\verb|VME_SYSRESET||
\VME_WRITE
CONFIG CLK
CONFIG DONE1
CONFIG_DONE2
CONFIG INIT1
CONFIG INIT2
LOC ADDR00
LOC ADDR01
LOC ADDR02
LOC_ADDR03
LOC_ADDR04
LOC_ADDR05
LOC_ADDR06
LOC ADDR07
LOC_ADDR08
LOC_ADDR09
LOC_ADDR10
LOC ADDR11
LOC ADDR12
LOC ADDR13
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LOC_ADDR14 LOC_ADDR15 LOC_ADDR16

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LOC_ADDR17
LOC_ADDR18
LOC ADDR19
LOC ADDR20 (required for Flash Am29LV116D)
LOC_CS_MAIN1
LOC_CS_MAIN2
LOC_CS_SLB1
LOC_CS_SLB2
LOC CS SLB3
LOC CS SLB4
LOC_CS_SLB5
LOC_CS_SLB6
LOC_DATA00
LOC_DATA01
LOC DATA02
LOC_DATA03
LOC_DATA04
LOC_DATA05
LOC_DATA06
LOC DATA07
LOC DATA08
LOC DATA09
LOC_DATA10
LOC_DATA11
LOC_DATA12
LOC DATA13
LOC_DATA14
LOC DATA15
             (up to 15 required by SLBs)
LOC_DATA16
LOC_DATA17
LOC DATA18 (very useful for spy fifos etc)
LOC_R/W
SCL
SDA
VME_A01
VME_A02
VME A03
VME\_A04
VME A05
VME_A06
VME_A07
VME A08
VME A09
VME_A10
VME A11
VME_A12
VME_A13
VME_A14
VME A15
VME_A16
VME A17
VME A18
VME A19
VME A20
VME A21
VME A22
VME_A23
VME_AM0
VME_AM1
VME AM2
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VME AM3

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VME AM4
VME AM5
VME DATA DIR B
VME DATA00
VME DATA01
VME DATA02
VME DATA03
VME DATA04
VME DATA05
VME DATA06
VME DATA07
VME DATA08
VME DATA09
VME DATA10
VME DATA11
VME DATA12
VME_DATA13
VME DATA14
VME DATA15
VME DATA16
VME DATA17
VME DATA18
VME DATA19
VME DATA20
VME DATA21
VME DATA22
VME DATA23
VME DATA24 (serial test points + jumper)
VME DATA25 (serial test points + jumper)
VME DATA26 (serial test points + jumper)
VME DATA27 (serial test points + jumper)
VME DATA28 (serial test points + jumper)
VME DATA29 (serial test points + jumper)
VME DATA30 (serial test points + jumper)
VME DATA31 (serial test points + jumper)
VME FPGA CLK40
VME LED1
VME LED2
VME TP1
VME TP2
VME SW1
VME SW2
             ===== special pins (verify that they are not counted as user i/o) =========
VME TCK
VME_TDI
VME_TDO
VME TMS
NCONFIG 1
NSTATUS 1
CONF DONE 1
EPC CLK 1
EPC DATA 1
                       == removed lines (compared to HTRproto) ======
\FLASH RESET (overwrite instead)
BASE0 BASE1 BASE2 (unused in HTRproto) CLOCK SELECT (from on-board switch)
\VME_BERR (just pull-down on the board) VME SYSCLK (can we leave it?)
VME A24 VME A25 VME A26 VME A27 VME A28 VME A29 VME A30 VME A31
LOC DATA19 LOC DATA20 LOC DATA21 LOC DATA22 LOC DATA23 LOC DATA24
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Put test points on the unused pins, including CLOCK2 (This pin can only be used as input or clock only).

======Programming Altera and Xilinx with JTAG======shouxiang wu wrote:

>

- > There should be no problem. You download Altera chip with Altera software and you download Xilinx chip with
- > Xilinx software. With an adapter cable, you can use Altera byteblaster as Xilinx parallel cable.

5. POWER CONSUMPTION ESTIMATE

| Component | P _{diss} x (# of components) | @ V | Source |
|---|--|------|-----------------------------------|
| Dual Opt. Receivers | $0.5 \text{ W} \times 8 = 4 \text{ W}$ | 3.3V | Data Sheet |
| Ch. Link TX | 0.1 W x 2 = 0.2 W | 3.3V | Data Sheet |
| SLB 3.3V [Vitesse=3W, $2 \times Altera = 2 \times 1W$] | 5 W x 6 = 30 W | 3.3V | Data Sheets |
| Xilinx XC2V3000bf957-4 | 0.1 W x 2 = 0.2 W | 3.3V | XPower (41 MHz,50% activity rate) |
| other | 1W | 3.3V | |
| Total from 3.3V | ≈36 W | | |
| | | | |
| TI TLK2501 | 260 mW x 16 = 4.2 W | 2.5V | Data Sheet |
| SLB 2.5V | 0.5 W | 2.5V | |
| Xilinx XC2V3000bf957-4 | 0.6 W x 2 = 1.2 W | 2.5V | XPower (41 MHz,50% activity rate) |
| Xilinx XC2V3000bf957-4 | 2.1 W x 2 = 4.2 W | 1.5V | XPower (41 MHz,50% activity rate) |
| | | | |
| Regulator for 2.5V National Semi. LM1084 | = output power ≈ 6W | +5V | |
| Regulator for 1.5V National Semi. LM1084 | > output power ≈ 4.2W | +5V | |
| Total from 5V | ≈ 25W | | |
| | | | |

Maximum front (VMEbus) 9U module power dissipation = 110W

Note: Each VME64x module has 6 +5V pins, 1 +5VSTDBY pin, 3 VPC (+5V) pins, 10 +3.3V pins, ... The pin power-rating curve given in VME64 allows approximately 1.5A per pin at 20°C. Thus each board has potentially 15A at +5V (75W), 15A at 3.3V (49.5W), ... The maximum power values ... are derived from acceptable power densities in the specified cooling environment. [see "TECHNICAL SPECIFICATION FOR SUBRACKS FOR LHC EXPERIMENTS" availab. on: http://atlas.web.cern.ch/Atlas/GROUPS/FRONTEND/documents/Crate Technical Specification final.pdf]

6. COST ESTIMATE

| 2 8-way optical ports | 2 x \$ 170= \$340 |
|---|--|
| 8 Dual LC O/E | 8 x \$ 100 = \$800 |
| 16 TLK2501 serdes | $16 \times 16 = 256$ |
| 2 xilinx FPGA | $2 \times \$472 = \$944 \text{ or } 2 \times \$743 = \$1486$ |
| 6 SLB mezzanine cards | $6 \times \$250 = \1500 |
| 1 TTCrx & mezzanine | \$ 200 |
| Other parts (Altera, buffers, connectors) | \$ 270 |
| | |
| Total parts | \$ 4150 or \$ 4700 |
| Total parts | \$ 4150 or \$ 4700 |
| Total parts PCB manufacturing | \$ 4150 or \$ 4700 \$ 300 |
| • | |
| PCB manufacturing | \$ 300 |